Preface

The special edition includes articles that represented the latest research results and engineering solutions in the area of electronic device design and production.

The first chapter is devoted to the analysis of the technological features of silicon carbide wafer fabrication for power electronics. Some technological operations such as etching, ion implantation, layer polishing, control of the crystal growing process, etc. are evaluated here.

Some research related to electronic packaging such as the validation of interfacial delamination, fabrication of nanocomposite material with graphene for the conductive substrate for flexible interconnection, analysis of transmission performance for fine pitch interconnect, etc. are presented in the second section.

The last section is dedicated to the practice of design and analysis of properties of some sensors, electronic and optoelectronic devices.

This special edition will be interesting to specialists in semiconductor power device production, microelectronics and optoelectronics.